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	•	Soldering instructions			
HARTING SFK 19 male	e standard connector solder straight RoHS				
	compliant	THR (Through Hole Reflow) connectors are designed to be used in a reflow can also be used together with SMD (Surface Mount Device) components in			
		called as well "Pin in hole intrusive reflow", the connectors are inserted in			
General information Design	IEC 60603-13	comparable way to conventional component mounting. All other components			
No. of contacts	6,10,14,16,20,24,26,30,34,40,50,60,64	The length of the connector contacts should be such that they protrude b			
Contact spacing	2,54 mm x 2,54 mm	after insertion to the PCB. Each contact collects solder on its tip as it pe			
Test voltage Ur.m.s	1 kV	in the hole. So if the contact is too long, this solder would no longer be a plated through hole by capillary action during the soldering process, there			
Working voltage Contact resistance	500 V for pollution degree 1 max. 20m0hm	soldered connection would suffer as a result.			
Insulation resistance	min. 10°0hm				
Working current acc. to IEC 60512-2	See derating diagram	Quantity of solder paste			
Temperature range Termination technology	-55°C +125°C solder	Before the components are assembled, solder paste must be applied to all			
Clearance & creepage distance	min. 0,5 mm clearance min. 0,56 creepage	(for connecting surface-mount components) and the plated through holes. To ensure that the plated through holes are completely filled, significantly paste must be applied than traditional solder pads on the PCB.			
	6-pole max. 12N for PL1-2 / 18N for PL3 ; 30-pole max. 60N for PL1-2 / 90N for PL3				
	10-pole max. 20N for PL1-2 / 30N for PL3 ; 34-pole max. 68N for PL1-2 / 102N for PL3	The following rule of thumb has proved valuable in practice:			
		Vpaste=2(VH-VP)			
_	14-pole max. 28N for PL1-2 / 42 for PL3 ; 40-pole max. 80N for PL1-2 / 120N for PL3	in which: VPaste = Required volume of solder paste VH= Volume of plated through hole			
Insertion and withdrawal forces	16-pole max. 32N for PL1-2 / 48N for PL3     ; 50-pole max. 100N for PL1-2 / 150N for PL3				
	20-pole max. 40N for PL1-2 / 60N for PL3 ; 60-pole max. 120N for PL1-2 / 180N for PL3	VP= Volume of the connector termination in the hole			
	24-pole max. 48N for PL1-2 / 72N for PL3 ; 64-pole max. 128N for PL1-2 / 192N for PL3	comment: the multiplier "2" compensates for solder paste shrinkage during			
	26-pole max. 52N for PL1-2 / 78N for PL3	For this purpose, it was assumed that 50% of the paste consists of the ac			
c	S4 surface treatment Au over PdNi (min. 0,76 µm)	the other 50% being soldering aids.			
	PL 1 acc. to IEC 60603-13 500 mating cycles 10 days gas test	Cross section of solder terminations			
Mating cycles	PL 2 acc. to IEC 60603-13 250 mating cycles 4 days gas test				
	PL 3 acc. to IEC 60603-13 50 mating cycles No gas test	0,525±0,025			
UL file	No				
RoHS – compliant	Yes				
Leadfree	Yes	P = 0,01			
Hot plugging	No				
Insulator material Material					
Color	PCT (thermoplastics, glass fiber reinforcement 30%) Black (RAL 7001) or beige				
D UL classification	UL94-V0				
Material group acc. IEC 60664-1	II (400 < CTI < 600)				
NF F 16-101 classification	No	× · ×			
Contact material Contact material		Packaging material (only for plastic tray)			
Plating termination zone	Copper alloy Sn over Ni				
Plating contact sliding side	Au or Au over PdNi (according to performance level)	Material Polystyrol			
		Color Yellow			
Derating diagram acc to IEC 60512-2 (Curren	t carrying capacity)	Standardization acc. to DIN EN / IEC 61340-5-1 and ANSI /			
The current carrying capacity is limited by					
of materials for inserts and contacts includ	ding terminals.	- Safe protection for electronic components against electrostatic charges			
E The current capacity-curve is valid for con current-loaded contacts of connectors when					
on all contacts is given without exceeding t	the maximum temperature.				
Control and test procedures according to D	IN IEC 60512.				
1) Temperature rise					
2) Derating					
3) Derating curve at I max x 0.8(IEC 60512-	2)	All Dimensions in mm Scale Free size tol.			
		Original Size DIN A3 1:1			
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	12     20     30     42     50     50     74     50     51     110     122     136       Ambient temperature [°C]       2     3     4     <	D-32339 Espelkamp Type DS Number 0919123			

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